

AN-2089 LMZ14203H/02H/01H Evaluation Board

1 Introduction

The LMZ14203H/02H/01H SIMPLE SWITCHER® power modules for high output voltage are easy-to-use DC-DC solutions capable of driving up to a 3A load with exceptional power conversion efficiency, output voltage accuracy, line and load regulation. They are available in an innovative package that enhances thermal performance and allows for hand or machine soldering.

The LMZ14203H/02H/01H Evaluation Board is configured for 12V output voltage from 15V to 42V input. The precision enable input allows for programmable UVLO of the input supply. The resistor voltage divider R_{ENT} and R_{ENB} set the input UVLO threshold. Connect the V_{IN} turret terminal to the EN turret on the board to enable operation.

The external soft-start capacitor C_{SS} facilitates controlled startup output rise time. The resistors R_{FBT} and R_{FBB} set the output voltage. An output feed-forward capacitor C_{FF} across the upper feedback resistor trims for optimum transient response. The control loop operates well with low ESR output capacitors such as ceramic and polymer electrolytic capacitors. The resistor R_{ON} sets the operating frequency. See datasheet for component selection details.

The LMZ14203H/02H/01H PCB layout offers excellent thermal performance, achieving junction-to-ambient thermal resistance θ_{JA} of 14.9°C/W. The evaluation board with its default Bill of Materials offers great EMI performance, complying with the EN 55022 Class B radiated emissions standard. The solution also complies with the CISPR22 conducted emissions standard with the addition of a small input filter.

2 Board Specifications

- $V_{IN} = 15V \text{ to } 42V$
- V_{OUT} = 12V
- 3A max load at 24V_{IN} and 65°C T_{AMB}
- Low radiated EMI (EN 55022 Class B compliant)
- · 400kHz switching frequency
- Enable UVLO set at 13.5V
- $\theta_{JA} = 14.9^{\circ}C/W$
- 4 copper layers
- 2 oz copper on top and bottom layer
- 1 oz copper on internal layers
- 6.985 cm x 7.620 cm (2.75 in x 3 in) with 1.575 cm (.062 in) thickness of FR4 laminate material

3 Additional Footprints

Additional component mounting pads are available to experiment with alternative input and output capacitor combinations or a zener clamp on the enable input. See Figure 6 for corresponding schematic locations.

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Additional Footprints www.ti.com

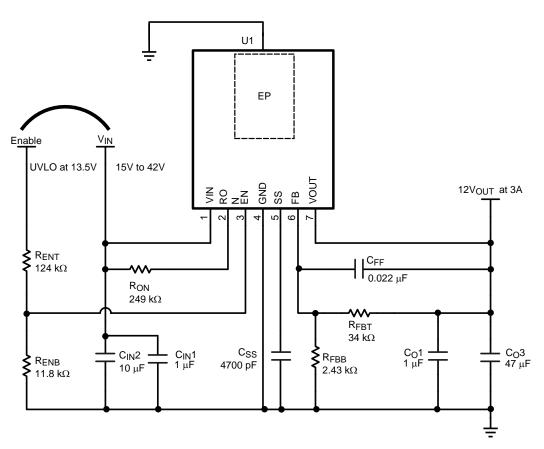


Figure 1. Evaluation Board Schematic

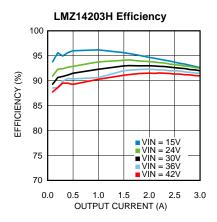
Table 1. LMZ1420xH Bill of Materials, V_{IN} = 15V to 42V, V_{OUT} = 12V, $I_{OUT\ (MAX)}$ = 3A / 2A / 1A

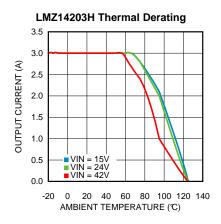
Designator	Description	Case Size	Manufacturer	Manufacturer P/N	Quantit y
U1	SIMPLE SWITCHER®	PFM-7	Texas Instruments	LMZ14203 or LMZ14202 or LMZ14201	1
C _{IN4} , C _{O1}	1 μF, X7R, 50V	1206	Taiyo Yuden	UMK316B7105KL-T	2
C _{IN2}	10 μF, X5R, 50V	1210	Taiyo Yuden	UMK325BJ106MM-T	1
C _{O3}	47 μF, 35 mΩ, 16V, Polymer	7343-43	KEMET	T525D476M016ATE035	1
C_{FF}	0.022 μF, X7R, 100V	0805	AVX	08051C223JAT2A	1
C _{SS}	4700 pF, X7R, 25V	0805	AVX	08053A472JAT2A	1
R _{ENB}	11.8 kΩ	0805	Panasonic	ERJ-6ENF1182V	1
R _{ENT}	124 kΩ	0805	Panasonic	ERJ-6ENF1243V	1
R_{FBT}	34 kΩ	0805	Vishay-Dale	CRCW080534K0FKEA	1
R_{FBB}	2.43 kΩ	0805	Panasonic	ERJ-6ENF2431V	1
R _{on}	249 kΩ	0805	Vishay-Dale	CRCW0805249KFKEA	1

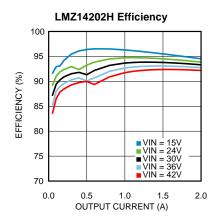


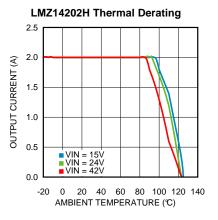
4 Performance Characteristics

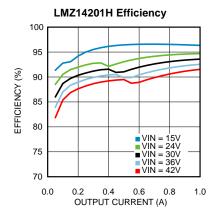
Unless otherwise specified the following conditions apply: $V_{IN} = 24V$, $V_{OUT} = 12V$, $T_{AMB} = 25$ °C

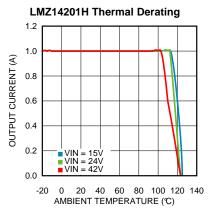




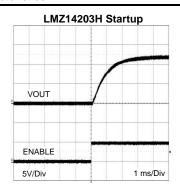


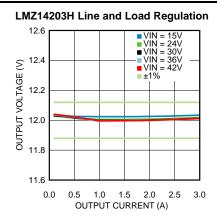


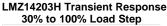


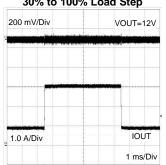


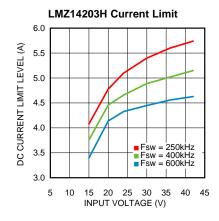


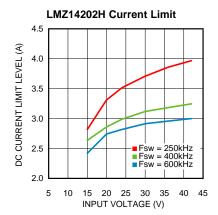


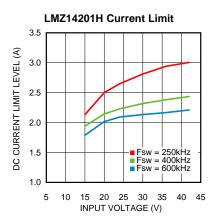






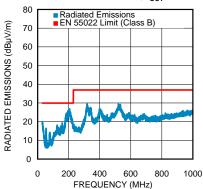




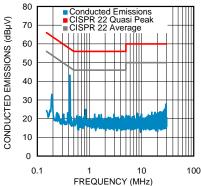




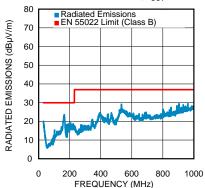
LMZ14203H Radiated EMI, $I_{OUT} = 3A$



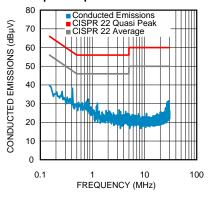
LMZ14203H Conducted EMI, $I_{OUT} = 3A$ with 3.3 μ H 2x10 μ F LC line filter added



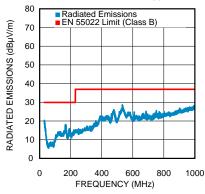
LMZ14202H Radiated EMI, I_{OUT} = 2A



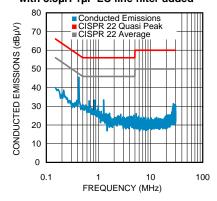
LMZ14202H Conducted EMI, I_{OUT} = 2A with 3.3µH 2x10µF LC line filter added



LMZ14201H Radiated EMI, $I_{OUT} = 1A$



LMZ14201H Conducted EMI, I_{OUT} = 1A with 3.3µH 1µF LC line filter added





PCB Layout Diagrams www.ti.com

5 PCB Layout Diagrams

Gerber and CAD files can be download from the LMZ14203H product folder.

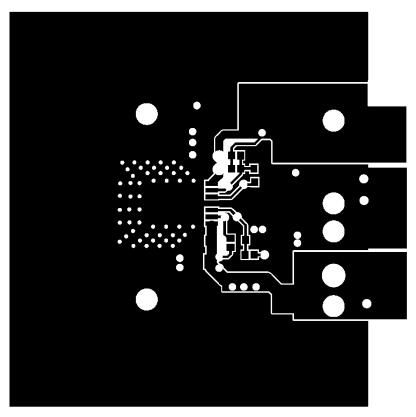


Figure 2. Top Layer



www.ti.com PCB Layout Diagrams

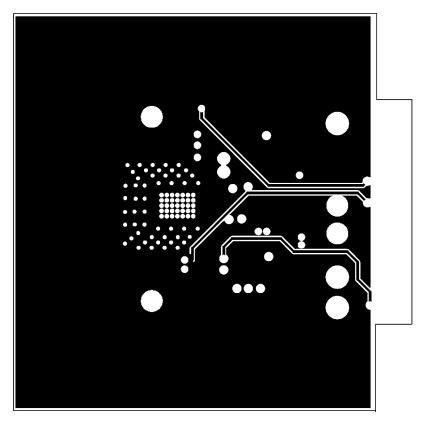


Figure 3. Internal Layer I (Ground) Heat Sinking Layer



PCB Layout Diagrams www.ti.com

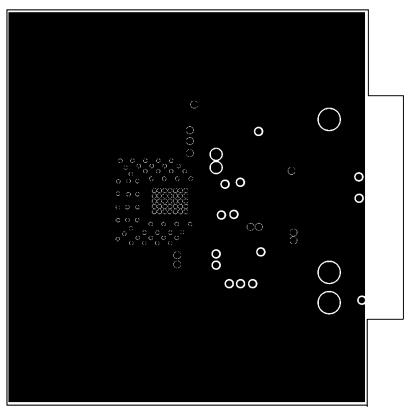


Figure 4. Internal Layer II (Ground) Heat Sinking Layer



www.ti.com PCB Layout Diagrams

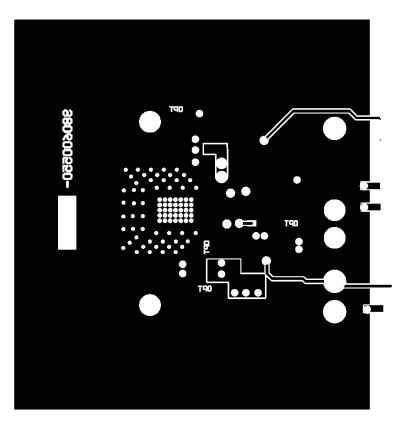


Figure 5. Bottom Layer (Ground and Routing) Heat Sinking Layer



PCB Schematic www.ti.com

6 PCB Schematic

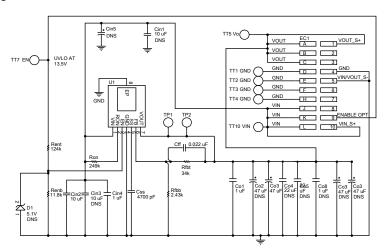


Figure 6. Detailed Schematic DNS = Component not installed

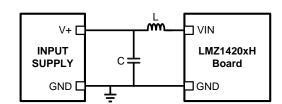


Figure 7. Conducted EMI LC Filter Configuration

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